

ABSTRACT

1. An encapsulating epoxy resin molding material, comprising  
(A) an epoxy resin, (B) a curing agent, and (C) an inorganic  
5 filler, wherein the inorganic filler (C) has an average particle  
size of 12  $\mu\text{m}$  or less and a specific surface area of 3.0  $\text{m}^2/\text{g}$   
or more.